











**TPS53820** 

ZHCSKW5-FEBRUARY 2020

## 适用于 Intel® CPU 电源且带 SVID 接口的集成降压转换器

### 1 特性

- 可支持 Intel VR13.HC SVID POL 应用的 单芯片
- 可支持 VCCANA (5.5A) 和 P1V8 (4A) 的两个输出
- 针对快速瞬态响应提供 D-CAP+™控制
- 宽输入电压范围 (4.5V 至 15V)
- 差动遥感
- 可编程内部环路补偿
- 每相逐周期电流限制
- 可编程开关频率范围为 800kHz 至 2MHz
- 用于电压、电流、功率、温度和故障条件遥测的 I<sup>2</sup>C 系统接口
- 过流、过压和过热保护
- 低静态电流
- 5mm x 5mm、35 引脚 QFN、PowerPAD 封装

#### 2 应用

• 适用于 Intel 服务器平台的低电流 SVID 电源轨

## 3 说明

TPS53820 器件是一款 D-CAP+ 模式集成降压转换器,可适用于 Intel CPU 电源的低电流 SVID 电源轨。它最多可提供两路输出来为低电流 SVID 电源轨(如 VCCANA (5.5A) 和 P1V8 (4A))供电。该器件采用 D-CAP+ 模式控制,可提供快速的负载瞬态性能。内部补偿可简化使用并减少外部器件。

该器件还提供针对输入电压、输出电压、输出电流和温度报告的遥测功能。此外,还提供过压、过流和过热保护。

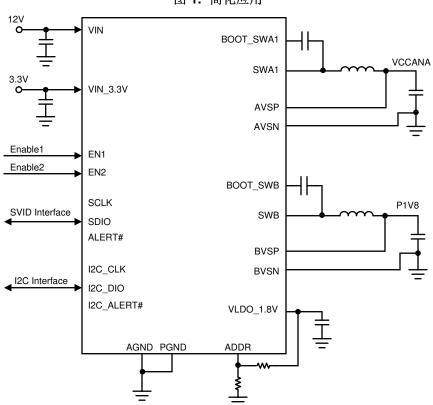
TPS53820 器件采用耐热增强型 35 引脚 QFN 封装, 工作温度范围为 -40°C 至 125°C。

表 1. 器件信息(1)

| 器件型号     | 封装       | 封装尺寸 (标称值) |
|----------|----------|------------|
| TPS53820 | RWZ (35) | 5mm × 5mm  |

(1) 如需了解所有可用封装,请参阅数据表末尾的可订购产品附录。

图 1. 简化应用





# TEXAS INSTRUMENTS

## 4 修订历史记录

注: 之前版本的页码可能与当前版本有所不同。

| 日期      | 修订版本 | 说明     |  |  |
|---------|------|--------|--|--|
| 2020年1月 | *    | 初始发行版。 |  |  |



## 5 器件和文档支持

## 5.1 商标

www.ti.com.cn

针对快速瞬态响应提供 D-CAP+ is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

#### 5.2 静电放电警告



ESD 可能会损坏该集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理措施和安装程序,可能会损坏集成电路。

**ESD** 的损坏小至导致微小的性能降级,大至整个器件故障。 精密的集成电路可能更容易受到损坏,这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。



## 6 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件的最新可用数据。数据如有变更,恕不另行通知,且 不会对此文档进行修订。如需获取此数据表的浏览器版本,请查阅左侧的导航栏。



www.ti.com.cn

## 6.1 Package Option Addendum

#### 6.1.1 Packaging Information

| Orderable Device | Status (1) | Package Type | Package<br>Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup>    | Lead/Ball<br>Finish <sup>(3)</sup> | MSL Peak Temp <sup>(4)</sup> | Op Temp (°C) | Device Marking <sup>(5)(6)</sup> |
|------------------|------------|--------------|--------------------|------|-------------|----------------------------|------------------------------------|------------------------------|--------------|----------------------------------|
| TPS53820RWZR     | ACTIVE     | VQFN-HR      | RWZ                | 35   | 3000        | Green (RoHS & no<br>Sb/Br) | NiPdAu                             | Level-2-260C-1 YEAR          | -40 to 125   | TPS53820                         |
| TPS53820RWZT     | ACTIVE     | VQFN-HR      | RWZ                | 35   | 250         | Green (RoHS & no<br>Sb/Br) | NiPdAu                             | Level-2-260C-1 YEAR          | -40 to 125   | TPS53820                         |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PRE\_PROD Unannounced device, not in production, not available for mass market, nor on the web, samples not available.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.
- (4) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (5) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device
- (6) Multiple Device markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

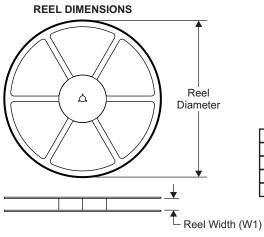
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

版权 © 2020, Texas Instruments Incorporated 5

# TEXAS INSTRUMENTS

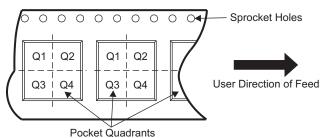
#### 6.1.2 Tape and Reel Information



# 

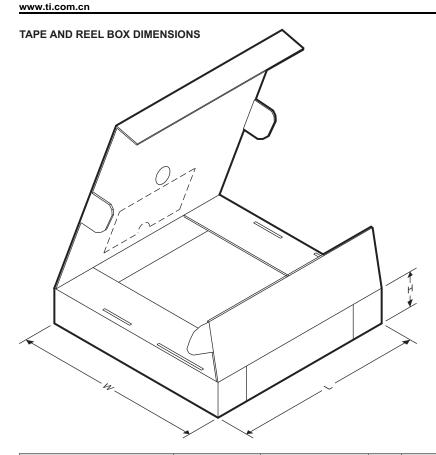
|    | Dimension designed to accommodate the component width     |
|----|---|
|    | Dimension designed to accommodate the component length    |
| K0 | Dimension designed to accommodate the component thickness |
| W  | Overall width of the carrier tape                         |
| P1 | Pitch between successive cavity centers                   |
|    |   |

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



| Device       | Package<br>Type | Package<br>Drawing | Pins | SPQ  | Reel<br>Diameter<br>(mm) | Reel<br>Width W1<br>(mm) | A0<br>(mm) | B0<br>(mm) | K0<br>(mm) | P1<br>(mm) | W<br>(mm) | Pin1<br>Quadrant |
|--------------|-----------------|--------------------|------|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| TPS53820RWZR | VQFN-HR         | RWZ                | 35   | 3000 | 330.0                    | 12.4                     | 5.3        | 5.3        | 1.1        | 8.0        | 12.0      | Q2               |
| TPS53820RWZT | VQFN-HR         | RWZ                | 35   | 250  | 180.0                    | 12.4                     | 5.3        | 5.3        | 1.1        | 8.0        | 12.0      | Q2               |





| Device       | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TPS53820RWZR | VQFN-HR      | RWZ             | 35   | 3000 | 367.0       | 367.0      | 35.0        |
| TPS53820RWZT | VQFN-HR      | RWZ             | 35   | 250  | 210.0       | 185.0      | 35.0        |

www.ti.com 9-Nov-2025

#### PACKAGING INFORMATION

| Orderable part number | Status | Material type | Package   Pins     | Package qty   Carrier | RoHS | Lead finish/<br>Ball material | MSL rating/<br>Peak reflow | Op temp (°C) | Part marking (6) |
|-----------------------|--------|---------------|--------------------|-----------------------|------|-------------------------------|----------------------------|--------------|------------------|
|                       |        |               |                    |                       |      | (4)                           | (5)                        |              |                  |
| TPS53820RWZR          | Active | Production    | VQFN-HR (RWZ)   35 | 3000   LARGE T&R      | Yes  | SN                            | Level-2-260C-1 YEAR        | -40 to 125   | TPS<br>53820     |
| TPS53820RWZR.A        | Active | Production    | VQFN-HR (RWZ)   35 | 3000   LARGE T&R      | Yes  | SN                            | Level-2-260C-1 YEAR        | -40 to 125   | TPS<br>53820     |
| TPS53820RWZT          | Active | Production    | VQFN-HR (RWZ)   35 | 250   SMALL T&R       | Yes  | SN                            | Level-2-260C-1 YEAR        | -40 to 125   | TPS<br>53820     |
| TPS53820RWZT.A        | Active | Production    | VQFN-HR (RWZ)   35 | 250   SMALL T&R       | Yes  | SN                            | Level-2-260C-1 YEAR        | -40 to 125   | TPS<br>53820     |

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

- (3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.
- (4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.



## **PACKAGE OPTION ADDENDUM**

www.ti.com 9-Nov-2025

### 重要通知和免责声明

TI"按原样"提供技术和可靠性数据(包括数据表)、设计资源(包括参考设计)、应用或其他设计建议、网络工具、安全信息和其他资源,不保证没有瑕疵且不做出任何明示或暗示的担保,包括但不限于对适销性、与某特定用途的适用性或不侵犯任何第三方知识产权的暗示担保。

这些资源可供使用 TI 产品进行设计的熟练开发人员使用。您将自行承担以下全部责任:(1) 针对您的应用选择合适的 TI 产品,(2) 设计、验证并测试您的应用,(3) 确保您的应用满足相应标准以及任何其他安全、安保法规或其他要求。

这些资源如有变更,恕不另行通知。TI 授权您仅可将这些资源用于研发本资源所述的 TI 产品的相关应用。严禁以其他方式对这些资源进行复制或展示。您无权使用任何其他 TI 知识产权或任何第三方知识产权。对于因您对这些资源的使用而对 TI 及其代表造成的任何索赔、损害、成本、损失和债务,您将全额赔偿,TI 对此概不负责。

TI 提供的产品受 TI 销售条款)、TI 通用质量指南 或 ti.com 上其他适用条款或 TI 产品随附的其他适用条款的约束。TI 提供这些资源并不会扩展或以其他方式更改 TI 针对 TI 产品发布的适用的担保或担保免责声明。 除非德州仪器 (TI) 明确将某产品指定为定制产品或客户特定产品,否则其产品均为按确定价格收入目录的标准通用器件。

TI 反对并拒绝您可能提出的任何其他或不同的条款。

版权所有 © 2025, 德州仪器 (TI) 公司

最后更新日期: 2025 年 10 月